

ABSTRACT

The present invention relates to a thermally and electrically conductive adhesive composition, which includes (A) an electrically conductive filler, (B) an epoxy resin, (C) a reactive diluent, and (D) a curing agent, wherein the electrically conductive filler (A) is a silver powder having an average particle diameter of 1 to 10 μm , the epoxy resin (B) has two or more epoxy functional groups and aromatic rings in each molecule, the reactive diluent (C) is a compound having two or more glycidyl ether functional groups in an aliphatic hydrocarbon chain and also having a molecular weight of 150 to 600, and the curing agent (D) is a compound having two or more phenol functional groups in each molecule, a compound having two or more aniline functional groups in each molecule, or a mixture of these compounds, and the content of each of the electrically conductive filler (A), the epoxy resin (B), the reactive diluent (C), and the curing agent (D) is within a specific range. The thermally and electrically conductive adhesive composition of the present invention has high thermal conductivity and stable electrical conductivity.